

Data sheet

SAW Rx filter LTE band 14

Series/type: B2626

Ordering code: B39761B2626P810

Date: May 31, 2019

Version: 2.0

DCN: 80-PA243-331 Rev. A

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RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

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1 Application

- Low-loss SAW RF single filter for LTE band 14
- High out-of-band rejection
- Usable pass band: 10 MHz
- Filter impedance 50 Ω

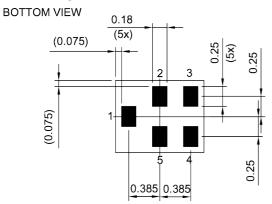
2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 1: -40 °C to +125 °C)



Figure 1: Picture of component with example of product marking.

3 Package



Pad and pitch tolerance ±0.05

4 Pin configuration

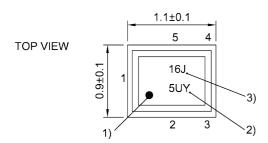
■ 1 Input

■ 4 Output

■ 2, 3, 5 Ground

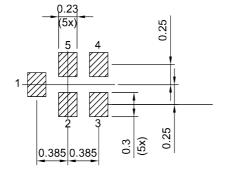
SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number





Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

5 Matching circuit

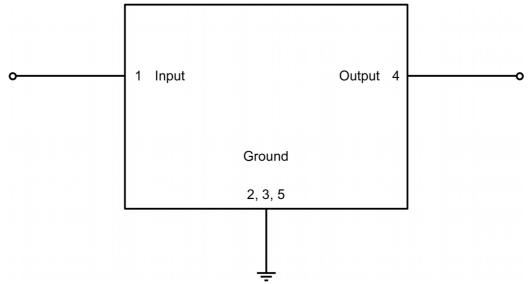


Figure 3: Schematic of matching circuit. No external matching components required.



6 Characteristics

Temperature range for specification $T_{\text{SPEC}} = -40 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$

Input terminating impedance $Z_{\rm IN} = 50~\Omega$ Output terminating impedance $Z_{\rm OUT} = 50~\Omega$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f _C	_	763	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	758 768	MHz		_	2.0	3.0	dB
Amplitude ripple (p-p)			Δα				
	758 768	MHz		_	0.3	1.4	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	758 768	MHz		_	1.5	2.0	
@ output port	758 768	MHz		_	1.6	2.0	
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	50 698	MHz		56	65	_	dB
	698 716	MHz		55	63	_	dB
	716 728	MHz		52	60	_	dB
	777 787	MHz		25 ¹⁾	27	_	dB
	777 787	MHz		232)	27	_	dB
	777 787	MHz		22	27	_	dB
	788 798	MHz		35	38	_	dB
	798 6000	MHz		31	35	_	dB
	824 849	MHz		52	62	_	dB
	2274 2304	MHz		41	44	_	dB
	2400 2500	MHz		40	42	_	dB
	4900 5950	MHz		32	36	_	dB

Valid for temperature $T = +25 \,^{\circ}\text{C...} + 85 \,^{\circ}\text{C.}$

Valid for temperature $T = -20 \,^{\circ}\text{C...} + 85 \,^{\circ}\text{C.}$



7 Maximum ratings

Operable temperature	T _{OP} = −40 °C +125 °C	
Storage temperature	T _{STG} = −40 °C +125 °C	
DC voltage	$ V_{DC} ^{2)} = 0 \text{ V (max.)}$	
Input power	P _{IN}	
@ input port: 758 768 MHz	15 dBm	Continuous wave for 2000 h @ 50 °C.
@ input port: 788 798 MHz	15 dBm	Continuous wave for 2000 h @ 50 °C.

Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

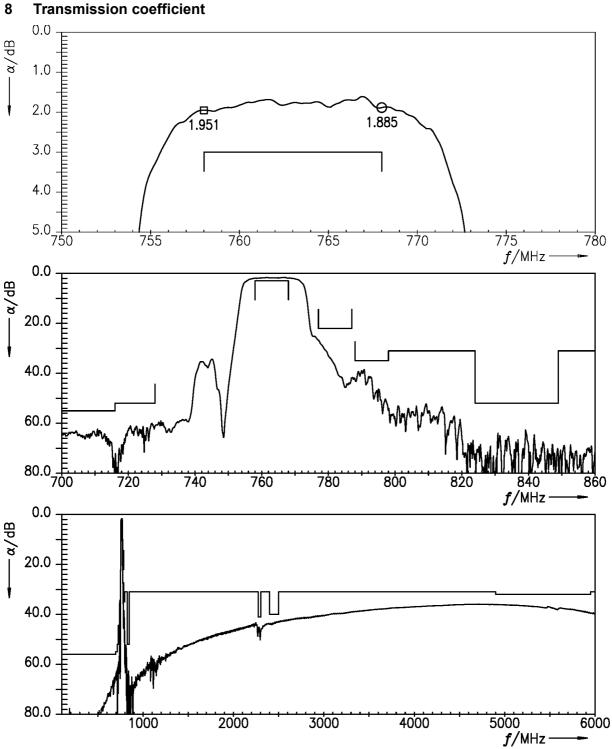
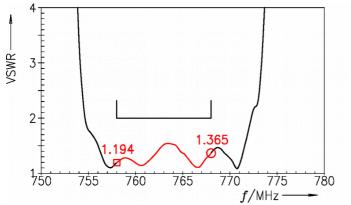


Figure 4: Attenuation.

9 Reflection coefficients



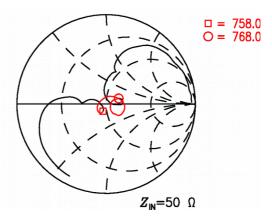
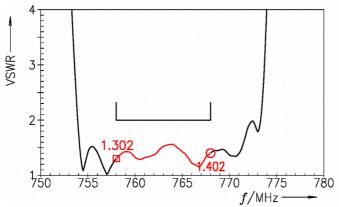


Figure 5: Reflection coefficient at input port.



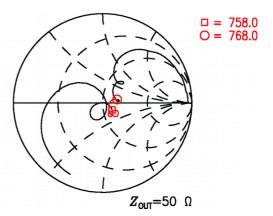


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

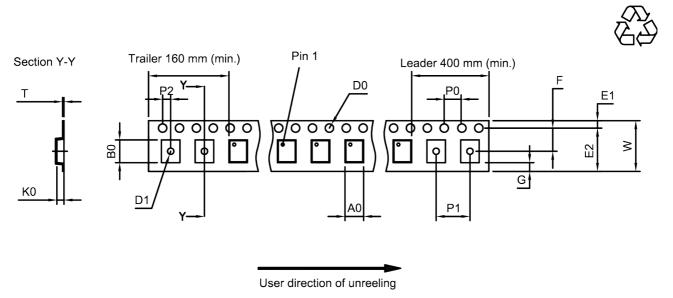


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.02±0.05 mm	E ₂	6.25 mm (min.)	_	P ₁	2.0±0.1 mm
B ₀	1.22±0.05 mm	F	3.5±0.05 mm		P_2	2.0±0.05 mm
D ₀	1.55±0.05 mm	G	_	_	Т	0.25±0.03 mm
D ₁	0.55±0.1 mm	K ₀	0.6±0.05 mm		W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm	- -		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

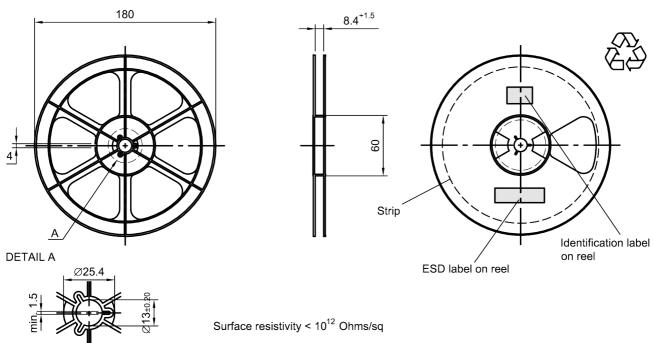


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

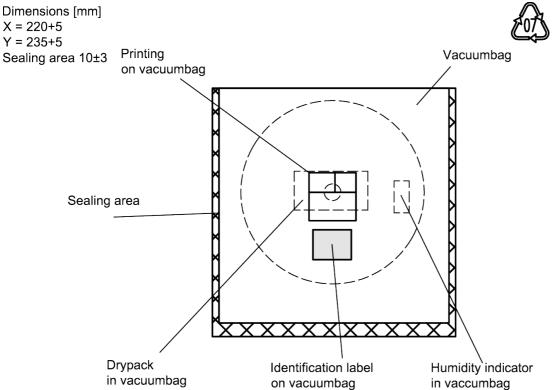


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

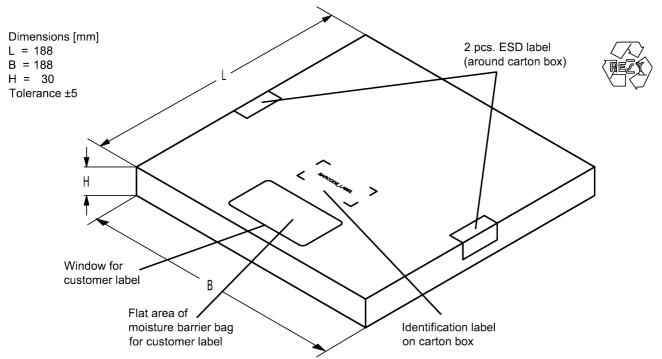


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x 32^2 + 6 x 32^1 + 18 (=J) x 32^0 = 1234

The BASE32 code for product type B2626 is 2J2.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ 12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	М	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	Х	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	X	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	V	
17	Н	41	١	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	M	45	<	
22	N	46	>	
23	Р			

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{\min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

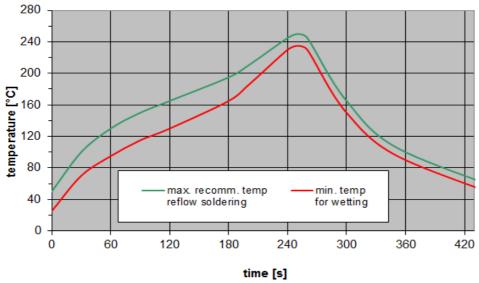


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 ESD protection of SAW filters

SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, "ESD matching" has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended "ESD matching" topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

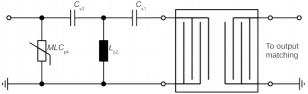


Figure 12: MLC varistor plus ESD matching.

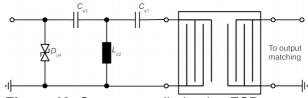


Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified "ESD matching" topologies can be used alternatively.

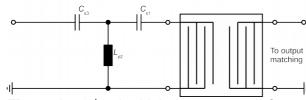


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: "**ESD protection for SAW filters**". This report can be found under www.rf360jv.com/rke. Click on "Applications Notes".



14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

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15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

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